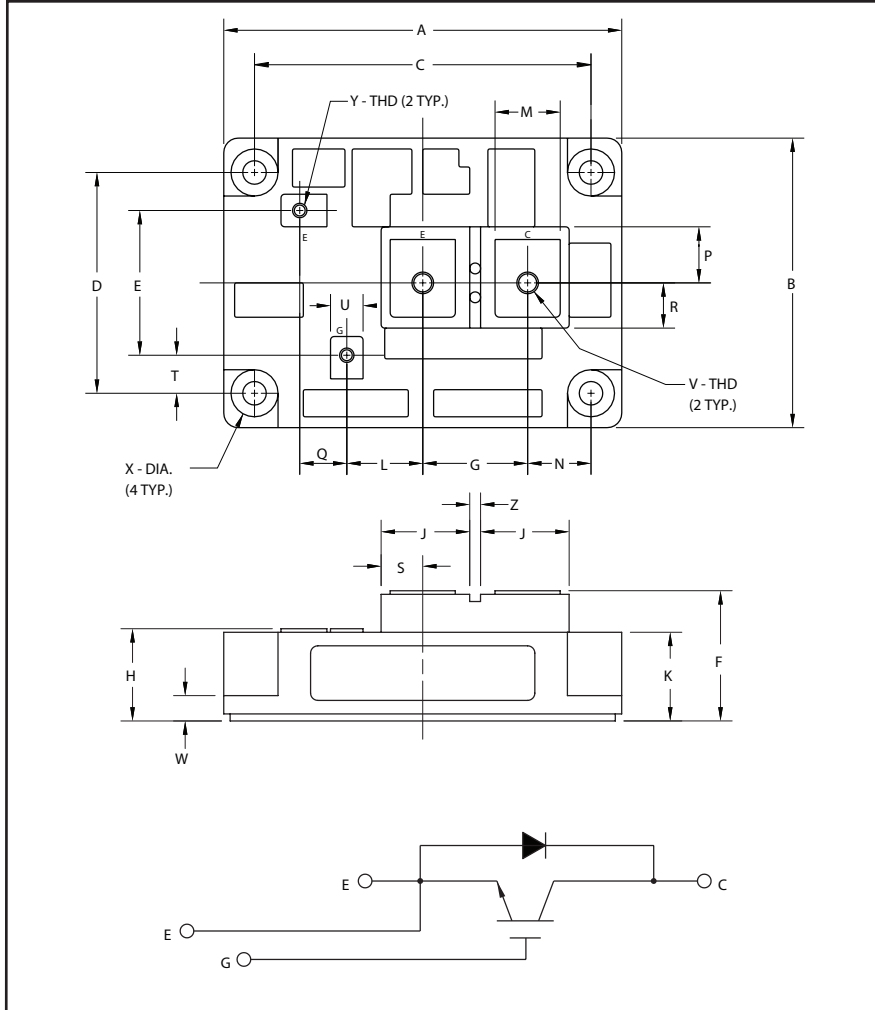


### Single IGBTMOD™ A-Series Module 600 Amperes/1200 Volts



Outline Drawing and Circuit Diagram

Dimensions	Inches	Millimeters
A	4.33	110.0
B	3.15	80.0
C	3.66±0.008	93.0±0.25
D	2.44±0.008	62.0±0.25
E	1.57	40.0
F	1.42 Max.	36.0 Max.
G	1.14	29.0
H	1.00 Max.	25.5 Max
J	0.94	24.5
K	0.94	24.5
L	0.83	21.0
M	0.71	18.0

Dimensions	Inches	Millimeters
N	0.69	17.5
P	0.61	15.5
Q	0.51	13.0
R	0.49	12.5
S	0.45	11.5
T	0.43	11.0
U	0.35	9.0
V	M8 Metric	M8
W	0.28	7.0
X	0.256 Dia.	6.50 Dia.
Y	M4 Metric	M4
Z	0.12	3.04



#### Description:

Powerex IGBTMOD™ Modules are designed for use in switching applications. Each module consists of one IGBT Transistor in a single configuration with a reverse connected super-fast recovery free-wheel diode. All components and interconnects are isolated from the heat sinking baseplate, offering simplified system assembly and thermal management.

#### Features:

- Low Drive Power
- Low  $V_{CE(sat)}$
- Discrete Super-Fast Recovery Free-Wheel Diode
- Isolated Baseplate for Easy Heat Sinking

#### Applications:

- DC Chopper
- Inverter
- UPS
- Forklift

#### Ordering Information:

Example: Select the complete part module number you desire from the table below -i.e. CM600HB-24A is a 1200V ( $V_{CES}$ ), 600 Ampere Single IGBTMOD™ Power Module.

Type	Current Rating Amperes	$V_{CES}$ Volts (x 50)
CM	600	24



Powerex, Inc., 173 Pavilion Lane, Youngwood, Pennsylvania 15697 (724) 925-7272 www.pwr.com

**CM600HB-24A**  
**Single IGBTMOD™ A-Series Module**  
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**Absolute Maximum Ratings,  $T_j = 25^\circ\text{C}$  unless otherwise specified**

Ratings	Symbol	CM600HB-24A	Units
Junction Temperature	$T_j$	-40 to 150	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-40 to 125	$^\circ\text{C}$
Collector-Emitter Voltage (G-E Short)	$V_{CES}$	1200	Volts
Gate-Emitter Voltage (C-E Short)	$V_{GES}$	$\pm 20$	Volts
Collector Current (DC, $T_C = 80^\circ\text{C}$ )*4	$I_C$	600	Amperes
Peak Collector Current (Pulse, Repetitive)*2	$I_{CM}$	1200	Amperes
Maximum Collector Dissipation ( $T_C = 25^\circ\text{C}$ )*2,*4	$P_C$	3670	Watts
Emitter Current ( $T_C = 25^\circ\text{C}$ )	$I_E^{*1}$	600	Amperes
Peak Emitter Current (Pulse, Repetitive)*2	$I_{EM}^{*1}$	1200	Amperes
Mounting Torque, M8 Main Terminal	—	95	in-lb
Mounting Torque, M6 Mounting	—	26	in-lb
Mounting Torque, M4 G(E) Terminal	—	13	in-lb
Weight	—	560	Grams
Isolation Voltage (Main Terminal to Baseplate, $f = 60\text{Hz}$ , AC 1 min.)	$V_{ISO}$	2500	Volts

**Static Electrical Characteristics,  $T_j = 25^\circ\text{C}$  unless otherwise specified**

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Collector-Cutoff Current	$I_{CES}$	$V_{CE} = V_{CES}, V_{GE} = 0V$	—	—	1.0	mA
Gate Leakage Current	$I_{GES}$	$V_{GE} = V_{GES}, V_{CE} = 0V$	—	—	1.5	$\mu\text{A}$
Gate-Emitter Threshold Voltage	$V_{GE(th)}$	$I_C = 60\text{mA}, V_{CE} = 10V$	6.0	7.0	8.0	Volts
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C = 600A, V_{GE} = 15V, T_j = 25^\circ\text{C}^{*3}$	—	2.1	3.0	Volts
		$I_C = 600A, V_{GE} = 15V, T_j = 125^\circ\text{C}^{*3}$	—	2.4	—	Volts
Total Gate Charge	$Q_G$	$V_{CC} = 600V, I_C = 600A, V_{GE} = 15V$	—	3000	—	nC
Emitter-Collector Voltage	$V_{EC}^{*1}$	$I_E = 600A, V_{GE} = 0V^{*3}$	—	—	3.8	Volts

**Dynamic Electrical Characteristics,  $T_j = 25^\circ\text{C}$  unless otherwise specified**

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Input Capacitance	$C_{ies}$		—	—	105	nf
Output Capacitance	$C_{oes}$	$V_{CE} = 10V, V_{GE} = 0V$	—	—	9	nf
Reverse Transfer Capacitance	$C_{res}$		—	—	2.0	nf
Inductive Load	Turn-on Delay Time	$t_d(on)$	—	—	660	ns
	Rise Time					
Switch Time	Turn-off Delay Time	$t_d(off)$	—	—	700	ns
	Fall Time					
Diode Reverse Recovery Time	$t_{rr}^{*1}$	Switching Operation,	—	—	250	ns
Diode Reverse Recovery Charge	$Q_{rr}^{*1}$	$I_E = 600A$	—	19.0	—	$\mu\text{C}$

\*1 Represents characteristics of the anti-parallel, emitter-to-collector free-wheel diode (FWDI).  
 \*2 Pulse width and repetition rate should be such that device junction temperature ( $T_j$ ) does not exceed  $T_{j(max)}$  rating.  
 \*3 Pulse width and repetition rate should be such as to cause negligible temperature rise.  
 \*4 Case temperature ( $T_C$ ), and heatsink temperature ( $T_f$ ) measured point is just under the chips.

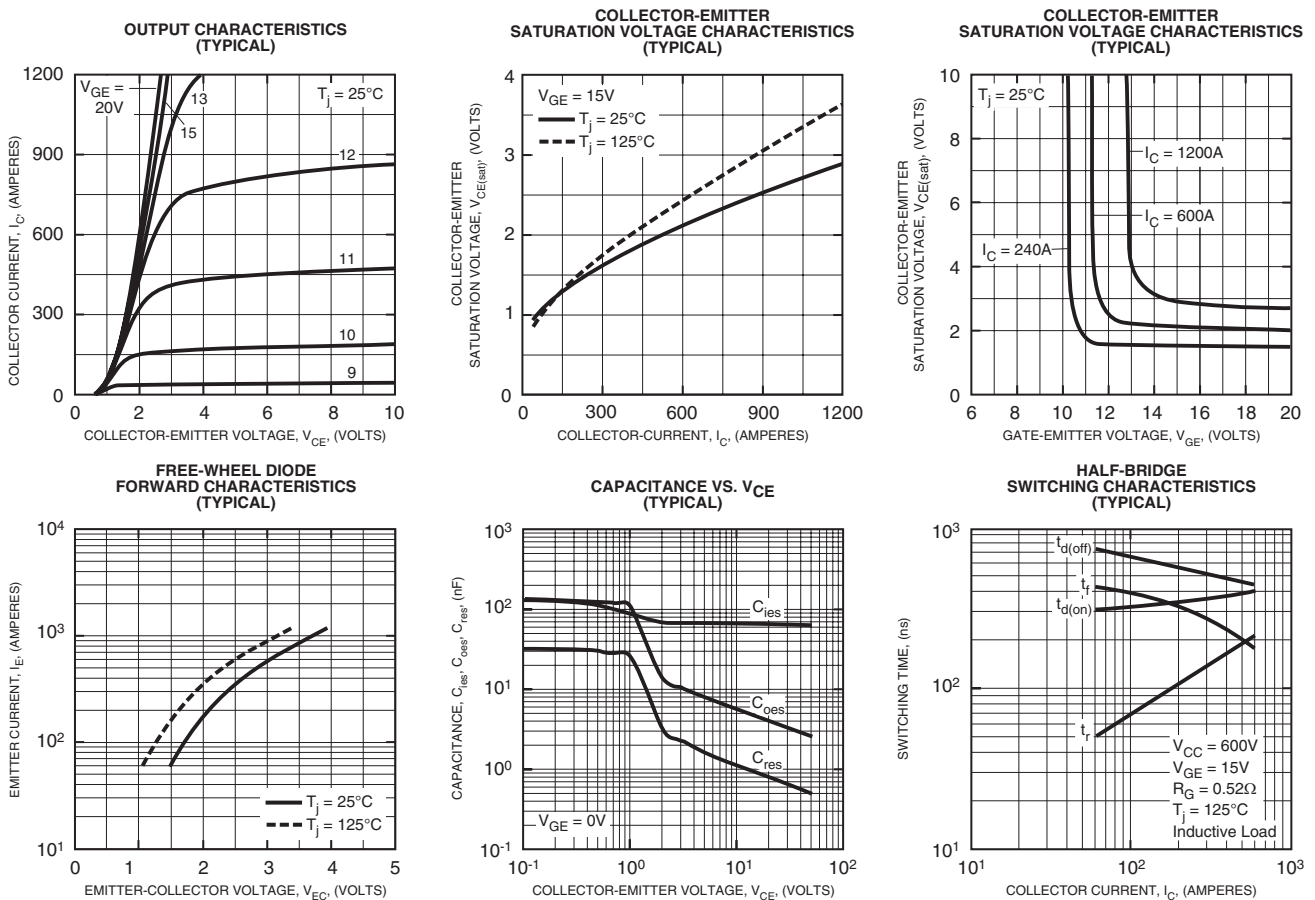
**CM600HB-24A**  
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**Thermal and Mechanical Characteristics,  $T_j = 25^\circ\text{C}$  unless otherwise specified**

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal Resistance, Junction to Case	$R_{th(j-c)Q}$	Per IGBT*4	—	—	0.034	$^\circ\text{C/W}$
Thermal Resistance, Junction to Case	$R_{th(j-c)D}$	Per FWDi*4	—	—	0.053	$^\circ\text{C/W}$
Contact Thermal Resistance	$R_{th(c-f)}$	Thermal Grease Applied*4,*5	—	0.02	—	$^\circ\text{C/W}$
External Gate Resistance	$R_G$		0.52	—	7.8	$\Omega$

\*4 Case temperature ( $T_C$ ), and heatsink temperature ( $T_f$ ) measured point is just under the chips.

\*5 Typical value is measured by using thermally conductive grease of  $\lambda = 0.9$  [W/(m • K)].





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